



## Materials Declaration Form


<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>25-05-2021</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement			
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Legal Statement			
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M95080-RDW6TP	PT6P*95081KA	A	3068	25-05-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	NAC	8	L Bend	
Comment	Package : 6P TSSOP 8 BODY 4.4 PITCH 0.65 0079397			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product









Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PT6P*95081KA				7000000.0	999973.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.508	mg	supplier	die	Silicon (Si)	7440-21-3		0.489	mg	962598	14382
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3937	59
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1969	29
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	31496	471
Lead-frame	M-011 Other inorganic materials	14.517	mg	supplier	alloy	Copper (Cu)	7440-50-8		14.147	mg	974500	416079
				supplier	alloy	Iron (Fe)	7439-89-6		0.341	mg	23460	10017
				supplier	alloy	Zinc (Zn)	7440-66-6		0.017	mg	1200	512
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	840	359
Lead-frame Coating	M-011 Other inorganic materials	0.062	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.058	mg	942580	1708
				supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	29665	54
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	27755	50
Die Attach	M-011 Other inorganic materials	0.049	mg	supplier	glue or soft solder	Silver(Ag)	7440-22-4		0.037	mg	760000	1095
				supplier	glue or soft solder	Oxiranylmethoxy-phenyl-methylene-bisoxiran	13561-08-5		0.006	mg	120000	173
				supplier	glue or soft solder	Phenol resin	9003-35-4		0.001	mg	30000	43
				supplier	glue or soft solder	Epoxypropoxy butane polymer	2425-79-8		0.001	mg	30000	43
				supplier	glue or soft solder	Diglycidyl phenyl allyl ether	EC 417-470-1		0.002	mg	50000	72
supplier	glue or soft solder	Polyoxypropylenediamine	9046-10-6		0.000	mg	10000	14				
Wires	M-011 Other inorganic materials	0.019	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.019	mg	1000000	546
Encapsulation	M-011 Other inorganic materials	18.844	mg	supplier	Moulding Compound	Epoxy Resin	85954-11-6		1.434	mg	76108	42183
				supplier	Moulding Compound	Phenol Resin	26834-02-6		0.956	mg	50739	28122
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		16.282	mg	864020	478882
				supplier	Moulding Compound	Carbon black	1333-86-4		0.096	mg	5074	2812
supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.076	mg	4059	2250				
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	940951	17
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	30507	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	28542	1







